

ABSTRACT

An electronic component attaching tool
suitable for an external shape of a semiconductor
device is prepared. The electronic component
5 attaching tool has a function of aligning a position
of the semiconductor device to an IC socket. The
electronic component attaching tool is mounted on
the standard surface that is formed on the IC socket
substantially regardless of the external shape of
10 the semiconductor device. The semiconductor device
is then aligned and attached to the IC socket by
using the electronic component attaching tool, and
the electronic component attaching tool is removed
from the IC socket. Another electronic component
15 attaching tool suitable for an external shape of
another semiconductor device is prepared, and the
same procedure as the above is performed to align
and attach this semiconductor device to the same
type IC socket.

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